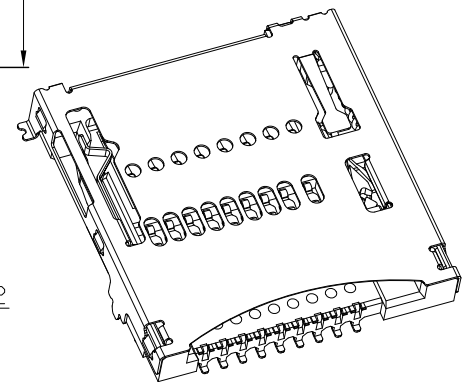
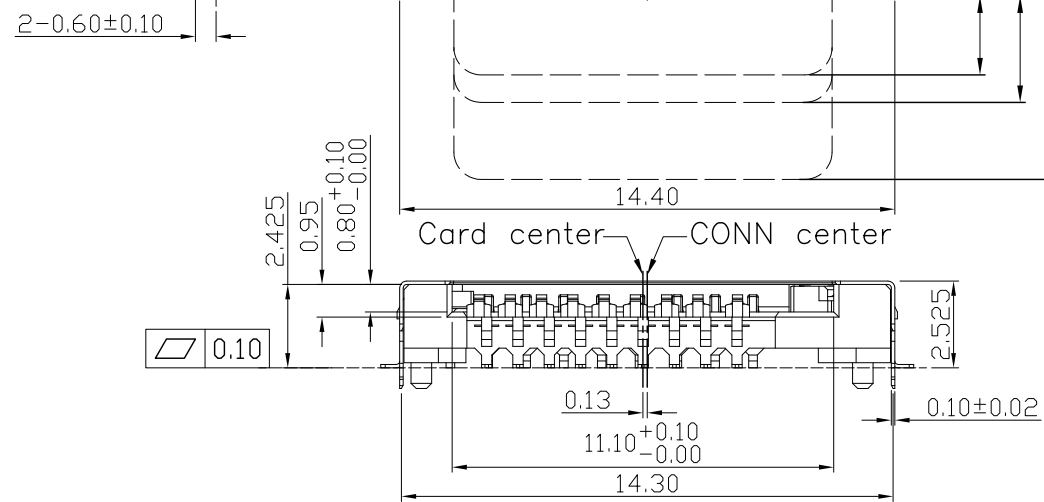
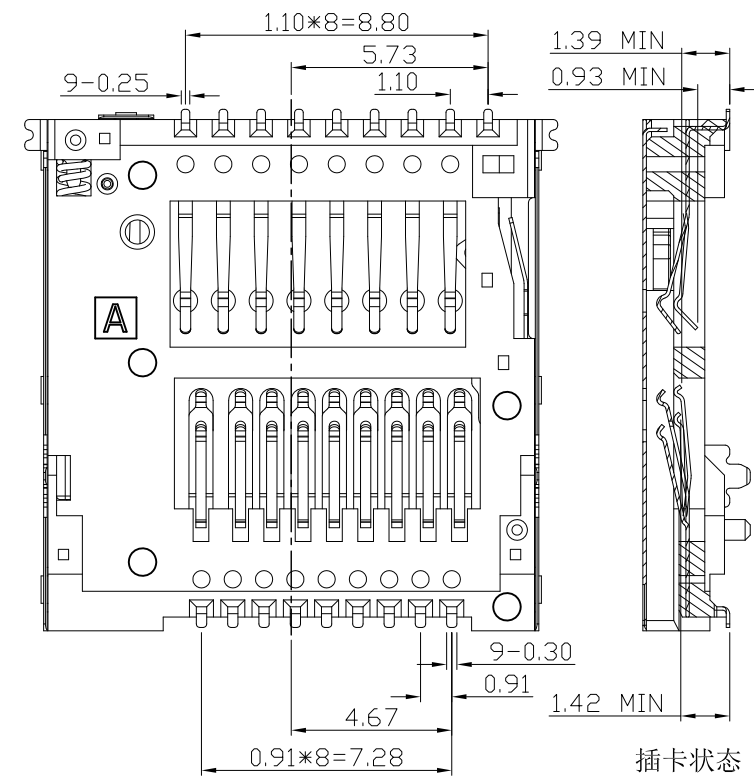
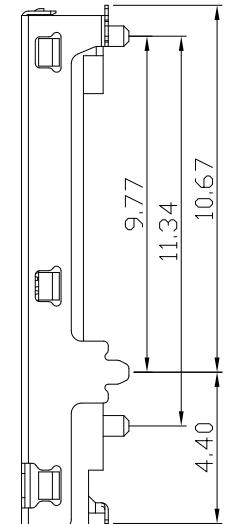
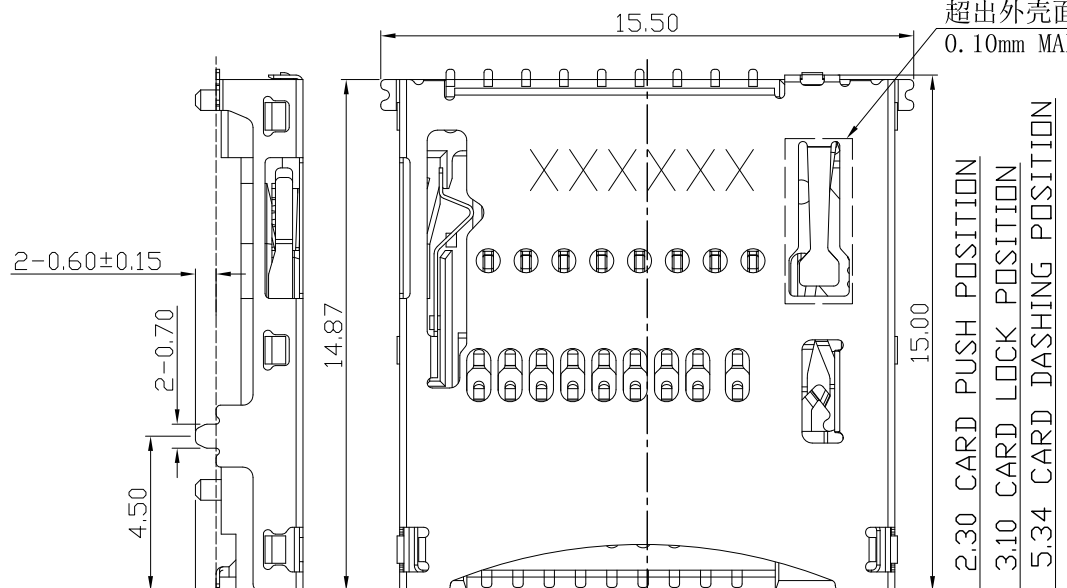
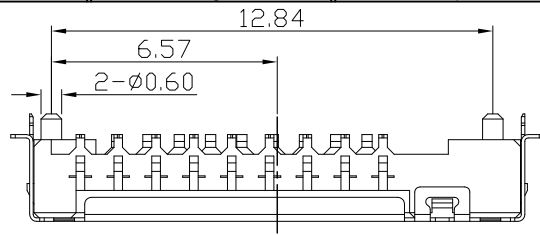


RoHS Compliant HF

REV.	ECN.NO.	MODIFY.CONTENT
A	/	NEW

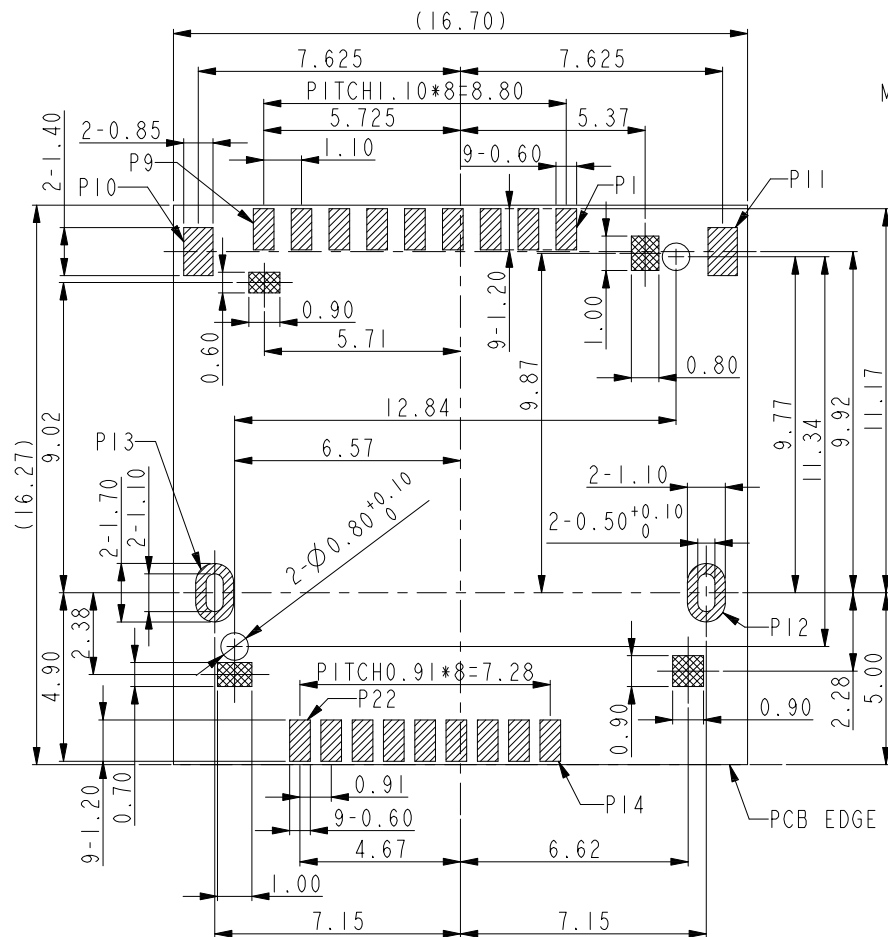


PART.NO.:
MR264-AP401-**

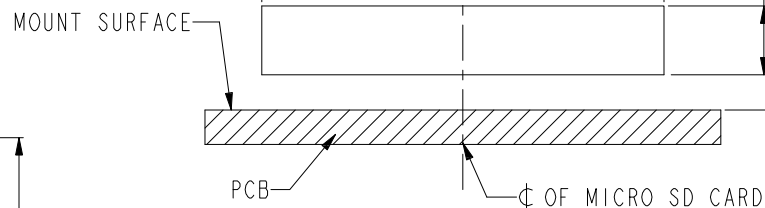
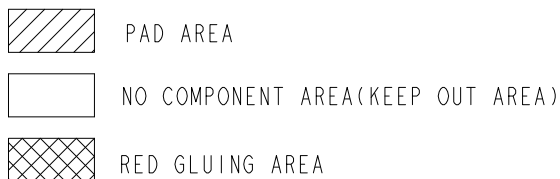
- 42: 功能区镀金1U", 锡脚镀雾纯锡至少80U"
- 43: 功能区镀金3U", 锡脚镀雾纯锡至少80U"
- 44: 功能区镀金5U", 锡脚镀雾纯锡至少80U"
- 45: 功能区镀金10U", 锡脚镀雾纯锡至少80U"
- 46: 功能区镀金15U", 锡脚镀雾纯锡至少80U"
- 47: 功能区镀金30U", 锡脚镀雾纯锡至少80U"

GENERAL TOLERANCE	DWG.NO.	MR264-AP401-00	PART.NO.	MR264-AP401-**	DRAWN	L.M.J 2021.07.28
x.±0.50	REV.	A	TITLE	Micro SD7.10 Push H2.525 conn.	CHECKED	
.x±0.25	SIZE	A4	SHEET	1/3	APPROVED	
.xx±0.15						

UNIT	mm	SCALE	1:1
东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			



RECOMMENDED P.C.B LAYOUT
TOP VIEW(TOLERANCE+/-0.05)



RECOMMEND ID DIMENSION

NOTES :

- MATERIAL :
 - HOUSING:LCP UL94 V-0, BLACK COLOR.
 - SHELL: STAINLESS STEEL
 - CONTACT: COPPER ALLOY
- FINISH :
 - CONTACT: CONTACT AREA SEE PART.NO, MATTE TIN 80u"MIN ON SOLDER TAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - SHELL: 30u" MIN NICKEL PLATING OVERALL.
- ELECTRICAL CHARACTERISTICS:
 - OPERATING VOLTAGE : 100V AC(rms)/DC.
 - CURRENT RATING : 0.5 A.
 - OPERATING TEMPERATURE: -25°C~+85°C.
 - CONTACT RESISTANCE: 100 m OHMS MAX.
 - INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
 - DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

PIN ASSIGNMENT

PIN NO.	MICRO SD EXPRESS CARD
P1	MICRO SD DAT2/CLKREQ#
P2	MICRO SD CD/DAT3/PERST#
P3	MICRO SD CMD
P4	MICRO SD V _{DD1}
P5	MICRO SD CLK
P6	MICRO SD V _{SS}
P7	MICRO SD DAT0/REFCLK+
P8	MICRO SD DAT1/REFCLK-
P9	MICRO SD CD
P10	GND
P11	GND
P12	GND
P13	GND
P14	MICRO SD V _{DD2}
P15	MICRO SD VDD3
P16	MICRO SD V _{SS}
P17	MICRO SD PCIE TX+
P18	MICRO SD PCIE TX-
P19	MICRO SD V _{SS}
P20	MICRO SD PCIE Rx-
P21	MICRO SD PCIE Rx+
P22	MICRO SD V _{SS}

OPENING/CLOSE OF SWITCH

	CARD DETECT SWITCH
CARD UNINSERTION	OPEN
CARD HALF INSERTION	OPEN
CARD INSERTION	CLOSE
N/O	

GENERAL TOLERANCE	DWG.NO.	PART.NO.	DRAWN	UNIT	SCALE
x.±0.50	MR264-AP401-00	MR264-AP401-*	L.M.J 2021.07.28	mm	1:1
x.±0.25	REV. A	TITLE	CHECKED		
.xx±1°	SIZE A4	SHEET 2/3	APPROVED		

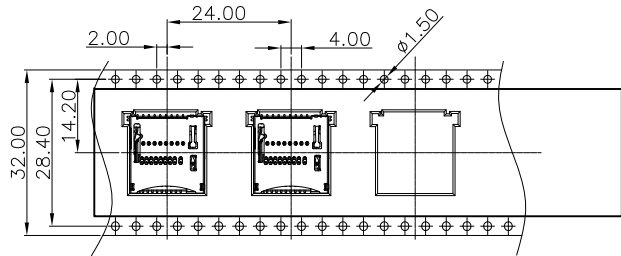
东莞市欧联电子科技有限公司

包装作业规范

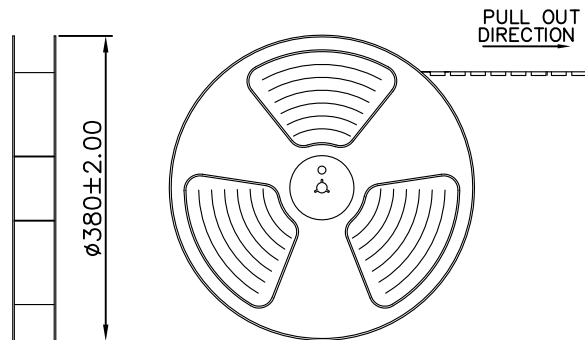
REV.	ECN.NO.	MODIFY.CONTENT
A	/	NEW

包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

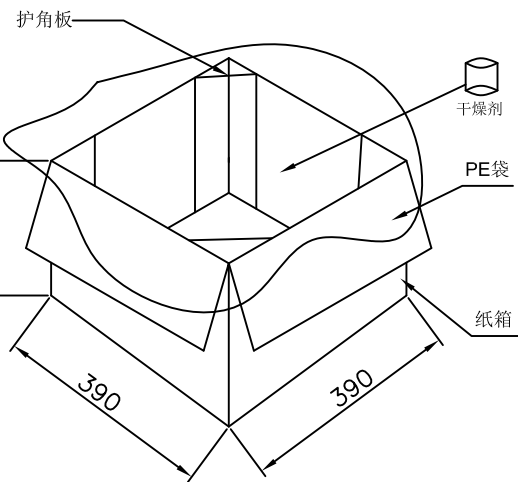
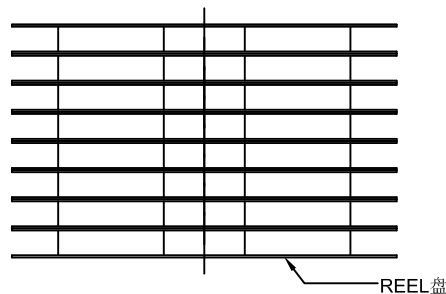
- 一.
- 1) 将成品一一放入REEL包装盘内, 依同一方向放入.
 - 2) 包装时, 如下图所示.
 - 3) 一个REEL包装盘放置800个成品.



- 二.
- 1) 装盘前先把前面空15格, 然后再开始装盘, 尾端也需空出15格, 上带加长200mm.
 - 2) 装满成品的REEL包装盘如下图所示.



- 三.
- 1) 每箱装 8 盘REEL包装盘.
 - 2) 每箱放置 6400 PCS 的成品.



- 四.
- 1) 用TAPE将纸箱封实.



備註 (REMARK)

1. 若有未装满之零数箱, 必须以缓冲材塞满.

GENERAL TOLERANCE	DWG.NO.	PART.NO.	DRAWN
x.±0.50	MR264-AP401-00	MR264-AP401-**	L.M.J 2021.07.28
x.°±5°	REV.	TITLE	CHECKED
.x±0.25	A	Micro SD7.10 Push H2.525 conn.	
.x°±2°	SIZE	SHEET	APPROVED
.xx±0.15	A4	3/3	

UNIT	mm	SCALE	1:1
东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			